

FAST RECOVERY RECTIFIERS

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0 Idea for
- ◆ printed circuit board
- ◆ Fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250 °C/ 10 seconds at terminals

Mechanical Data

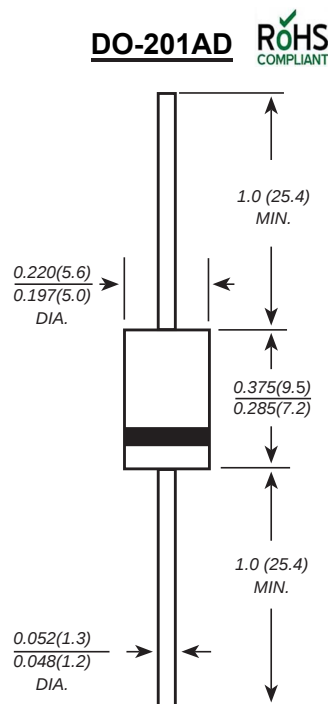
Case : JEDEC DO-201AD Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.04 ounce, 1.10 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	FR301	FR302	FR303	FR304	FR305	FR306	FR307	UNITS
Marking Code		MDD FR301	MDD FR302	MDD FR303	MDD FR304	MDD FR305	MDD FR306	MDD FR307	
Maximum repetitive peak reverse voltage	V _{RMM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at T _A =75℃	I _(AV)	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	150							A
Maximum instantaneous forward voltage at 3.0A	V _F	1.30							V
Maximum DC reverse current T _A =25℃ at rated DC blocking voltage T _A =100℃	I _R	5.0 100.0							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (NOTE 2)	C _J	60.0							pF
Typical thermal resistance (NOTE 3)	R _{θJA}	20.0							℃/W
Operating junction and storage temperature range	T _J , T _{STG}	-65 to +150							℃

Note: 1. Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$

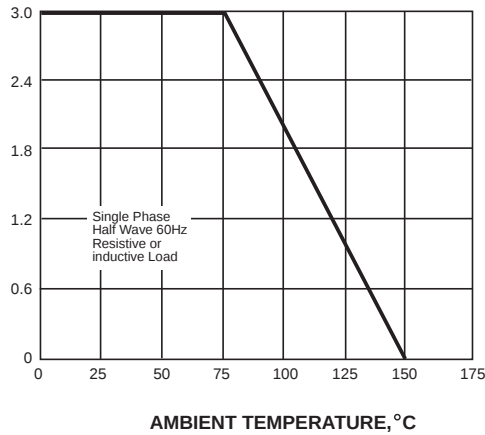
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3. Thermal resistance from junction to ambient at 0.375" (9.5mm) lead length, P.C.B. mounted

Ratings And Characteristic Curves

AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

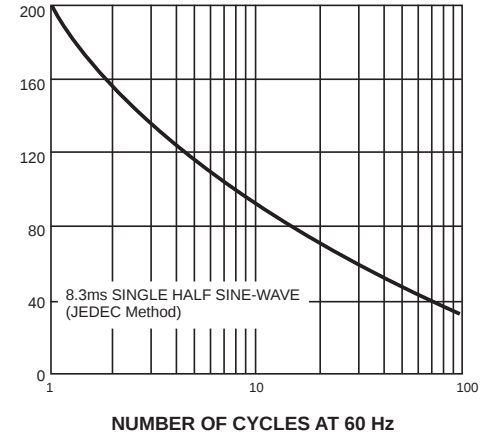
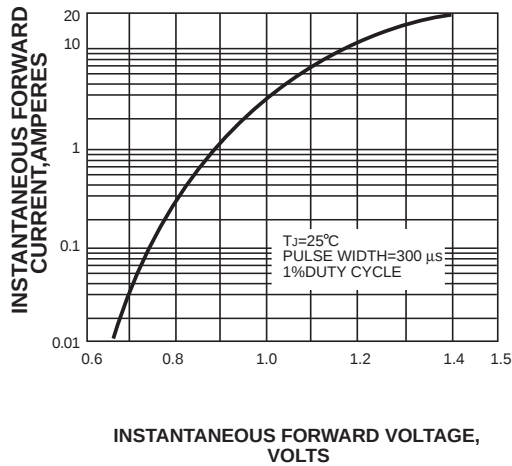


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



INSTANTANEOUS REVERSE CURRENT,
MICROAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS

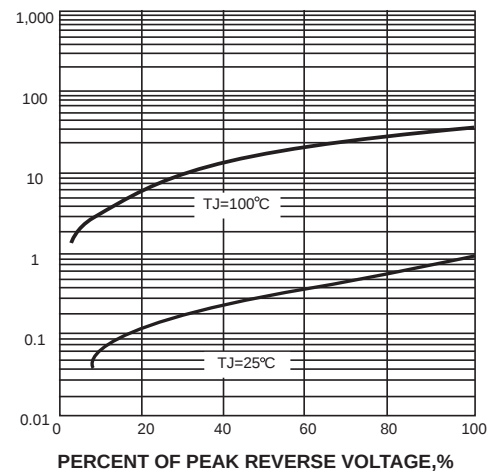
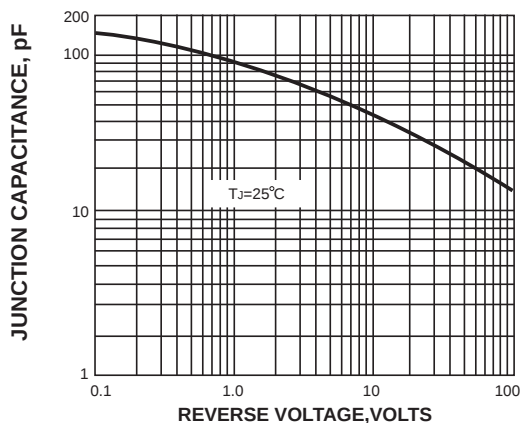
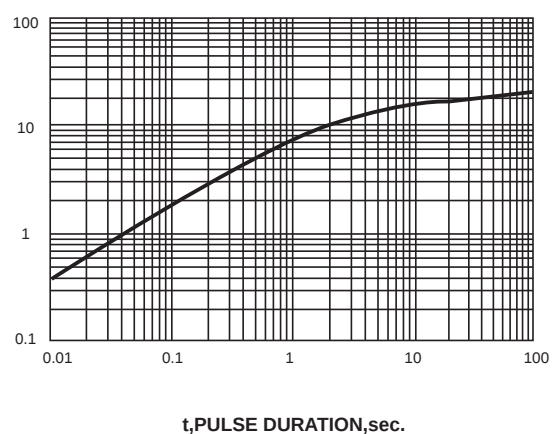


FIG. 5-TYPICAL JUNCTION CAPACITANCE



TRANSIENT THERMAL IMPEDANCE,
°C/W

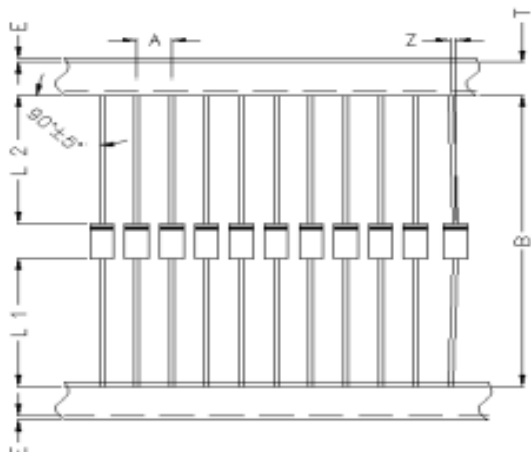
FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



The curve above is for reference only.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	10.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
DO - 201AD	255*74*145	1000	410*275*340	10000

Bulk Package Specifications

Package	Inner Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
DO - 201AD	198*86*21	200	460*220*250	10000

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